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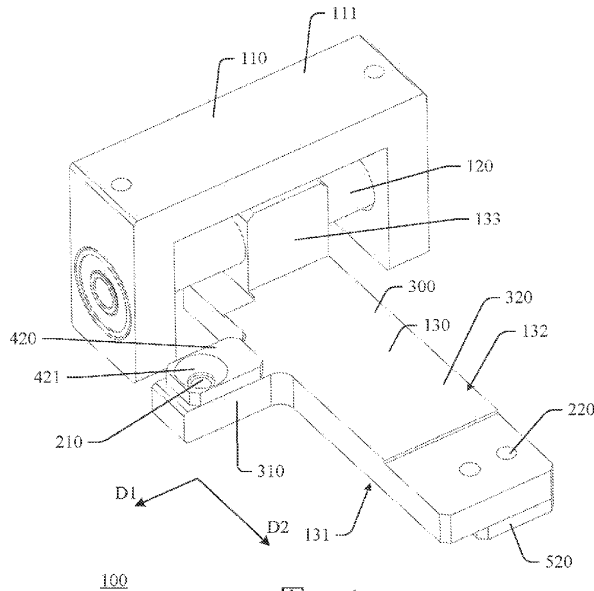
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(54) Title: PRESSURE MONITORING APPARATUS, SEMICONDUCTOR CLEANING DEVICE, AND MONITORING METHOD THEREFOR

(54) 发明名称: 压力监测装置、半导体清洗设备及其监测方法



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(57) Abstract: The present application provides a pressure monitoring apparatus, a semiconductor cleaning device, and a monitoring method therefor. The pressure monitoring apparatus comprises: a mounting frame, a swing rod, and a pressure sensor; the mounting frame is configured to fixedly connect the pressure monitoring apparatus to a device under test; the swing rod is rotatably connected to the mounting frame, a force receiving element is located on a first side of the swing rod, the pressure sensor is located on a second side of the swing rod, the first side and the second side are arranged opposite to each other, and when the swing rod is stressed, the

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swing rod swings between the force receiving element and the pressure sensor; a first pressure contact portion and a second pressure contact portion are arranged on the swing rod, the first pressure contact portion protrudes towards the first side, and the second pressure contact portion protrudes towards the second side and is in contact with the pressure sensor; and when the force receiving element is stressed, the pressure is transmitted to the first pressure contact portion and enables the swing rod to swing, so that the second pressure contact portion transmits the pressure to the pressure sensor.

(57) 摘要: 本申请提供了一种压力监测装置、半导体清洗设备及其监测方法。该压力监测装置包括: 安装架、摆动杆和压力传感器, 安装架用于将压力监测装置与被测设备固定连接; 摆动杆与安装架可转动地连接, 受力元件位于摆动杆的第一侧, 压力传感器位于摆动杆的第二侧, 第一侧与第二侧相对设置, 当摆动杆受力时, 摆动杆在受力元件和压力传感器之间摆动; 摆动杆上设置有第一压力接触部和第二压力接触部, 第一压力接触部朝向第一侧凸出设置, 第二压力接触部朝向第二侧凸出设置并且接触压力传感器; 其中, 当受力元件受到压力时, 压力被传递至第一压力接触部并使摆动杆摆动, 使第二压力接触部将压力传递至压力传感器。